Standard 32K x 8 SRAM

Features

☐ 32768x8 bit static CMOS RAM ☐ Access times 70 ns, 100 ns Common data inputs and data outputs ☐ Three-state outputs □ Typ. operating supply current 70 ns: 50 mA 100 ns: 40 mA TTL/CMOS-compatible ☐ Automatical reduction of power dissipation in long Read Cycles □ Power supply voltage 5 V ± 10 % Operating temperature ranges 0 to 70 °C -40 to 85 °C CECC 90000 Quality Standard ☐ ESD protection > 2000 V (MIL STD 883C M3015.7) ☐ Latch-up immunity >100 mA ☐ Package: SOP28 (330 mil)

Description

The U62256 is a static RAM manufactured using a CMOS process technology with the following operating modes:

- Read - Write

- Standby

- Data Retention The memory array is based on a

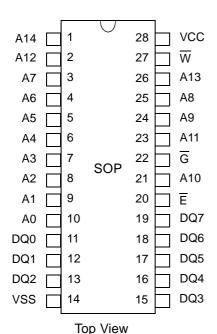
MIXMOS cell.

The circuit is activated by the falling edge of E. The address and control inputs open simultaneously. According to the information of \overline{W} and \overline{G} , the data inputs, or outputs, are active. In a Read cycle, the data outputs are activated by the falling edge of \overline{G} , afterwards the data word read will be available at the outputs DQ0-DQ7. After the address change, the data outputs go High-Z until the new information read is available. The data outputs have not preferred state. The Read cycle is finished by the

falling edge of \overline{W} , or by the rising edge of \overline{E} , respectively.

Data retention is guaranteed down to 2 V. With the exception of E, all inputs consist of NOR gates, so that no pull-up/pull-down resistors are required.

Pin Configuration



Pin Description

Signal Name	Signal Description
A0 - A14	Address Inputs
DQ0 - DQ7	Data In/Out
Ē	Chip Enable
G	Output Enable
W	Write Enable
VCC	Power Supply Voltage
VSS	Ground



Block Diagram A6 Α7 \bigcirc Memory Cell Α8 Row Decoder Arráy Α9 A10 512 Rows x A11 0 64 x 8 Columns A12 0 A13 O A14 Column Decoder Column Address Inputs A0 Α1 DQ0 A2 Sense Amplifier/ АЗ \bigcirc -○ DQ1 Write Control Logic A4 Common Data I/O ►O DQ2 Α5 ►O DQ3 **-**○ DQ4 **►**○ DQ5 Address Clock Change Detector ►O DQ6 Generator ►O DQ7 J 9 **Truth Table**

Operating Mode	Ē	w	G	DQ0 - DQ7
Standby/not selected	Н	*	*	High-Z
Internal Read	L	Н	Н	High-Z
Read	L	Н	L	Data Outputs Low-Z
Write	L	L	*	Data Inputs High-Z

 V_{SS}

 V_{CC}

W

G

Ē

Characteristics

All voltages are referenced to $V_{SS} = 0 V$ (ground).

All characteristics are valid in the power supply voltage range and in the operating temperature range specified.

Dynamic measurements are based on a rise and fall time of \leq 5 ns, measured between 10 % and 90 % of V_{II} , as well as input levels of V_{IL} = 0 V and V_{IH} = 3 V. The timing reference level of all input and output signals is 1.5 V,

with the exception of the t_{dis} -times and t_{en} -times, in which cases transition is measured ± 200 mV from steady-state voltage.

Maximum Ratings ^a		Symbol	Min.	Max.	Unit
Power Supply Voltage		V _{CC}	-0.5	7	V
Input Voltage		V _I	-0.5	V _{CC} + 0.5 ^b	V
Output Voltage		Vo	-0.5	V _{CC} + 0.5 ^b	V
Power Dissipation		P _D	-	1	W
Operating Temperature	C-Type K-Type	T _a	0 -40	70 85	°C
Storage Temperature		T _{stg}	-65	125	°C
Output Short-Circuit Curren at V _{CC} = 5 V and V _O = 0 V		I _{os}		200	mA

 ^a Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at condition above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability
 ^b Maximum voltage is 7 V

c Not more than 1 output should be shorted at the same time. Duration of the short circuit should not exceed 30 s.



^{*} H or L

Recommended Operating Conditions	Symbol	Conditions	Min.	Max.	Unit
Power Supply Voltage	V _{CC}		4.5	5.5	V
Input Low Voltage d	V _{IL}		-0.3	0.8	V
Input High Voltage	V _{IH}		2.2	V _{CC} + 0.3	V

d -2 V at Pulse Width 30 ns

Electrical Characteristics	Symbol	Conditio	ons Min.	Max.	Unit
Supply Current - Operating Mode	I _{CC(OP)}	$\begin{array}{ccc} V_{CC} & = 5. \\ V_{IL} & = 0. \\ V_{IH} & = 2. \\ t_{cW} & = 70 \\ t_{cW} & = 10 \end{array}$	8 V 2 V	70 65	mA mA
Supply Current - Standby Mode (CMOS level)	I _{CC(SB)}	$V_{CC} = 5.$ $V_{\overline{E}} = V_{C}$	5 V _{CC} - 0.2 V	50	μA
Supply Current - Standby Mode (TTL level)	I _{CC(SB)1}	$\begin{array}{ccc} V_{CC} & = 5. \\ V_{\overline{E}} & = 2. \end{array}$		10	mA
Output High Voltage	V _{OH}	V _{CC} = 4.	5 V 2.4 0 mA		V
Output Low Voltage	V _{OL}	$V_{CC} = 4.$		0.4	V
Input High Leakage Current	I _{IH}	V _{CC} = 5. V _{IH} = 5.		2	μA
Input Low Leakage Current	I _{IL}	$V_{CC}^{III} = 5.$			μA
Output High Current	I _{OH}	$V_{CC} = 4.$ $V_{OH} = 2.$		-1	mA
Output Low Current	l _{OL}	$\begin{array}{ccc} V_{OH} & = 2. \\ V_{CC} & = 4. \\ V_{OL} & = 0. \end{array}$	5 V 3,2		mA
Output Leakage Current High at Three-State Outputs	I _{OHZ}	V _{CC} = 5. V _{OH} = 5.		2	μА
Low at Three-State Outputs	I _{OLZ}	$V_{CC} = 5.$			μΑ

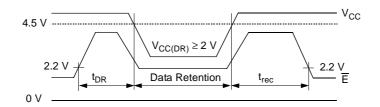
Switching Characteristics	Syn	nbol	0	7	10		Unit
Read Cycle	Alt.	IEC	Min.	Max.	Min.	Max.	Unit
Read Cycle Time	t _{RC}	t _{cR}	70		100		ns
Address Access Time to Data Valid	t _{AA}	t _{a(A)}		70		100	ns
Chip Enable Access Time to Data Valid	t _{ACE}	t _{a(E)}		70		100	ns
Output Enable Access Time to Data Valid	t _{OE}	t _{a(G)}		35		45	ns
E HIGH to Output in High-Z	t _{HZCE}	t _{dis(E)}		25		35	ns
G HIGH to Output in High-Z	t _{HZOE}	t _{dis(G)}		25		35	ns
E LOW to Output in Low-Z	t _{LZCE}	t _{en(E)}	5		5		ns
G LOW to Output in Low-Z	t _{LZOE}	t _{en(G)}	0		0		ns
Output Hold Time from Address Change	t _{OH}	t _{v(A)}	5		5		ns

Switching Characteristics	Syr	nbol	0	7	1	0	Unit
Write Cycle	Alt.	IEC	Min.	Max.	Min.	Max.	Ullit
Write Cycle Time	t _{WC}	t _{cW}	70		100		ns
Write Pulse Width	t _{WP}	t _{w(W)}	55		70		ns
Write Pulse Width Setup Time	t _{WP}	t _{su(W)}	55		70		ns
Address Setup Time	t _{AS}	t _{su(A)}	0		0		ns
Address Valid to End of Write	t _{AW}	t _{su(A-WH)}	65		80		ns
Chip Enable Setup Time	t _{CW}	t _{su(E)}	65		80		ns
Pulse Width Chip Enable to End of Write	t _{CW}	t _{w(E)}	65		80		ns
Data Setup Time	t _{DS}	t _{su(D)}	30		35		ns
Data Hold Time	t _{DH}	t _{h(D)}	0		0		ns
Address Hold from End of Write	t _{AH}	t _{h(A)}	0		0		ns
W LOW to Output in High-Z	t _{HZWE}	t _{dis(W)}		25		35	ns
G HIGH to Output in High-Z	t _{HZOE}	t _{dis(G)}		25		35	ns
W HIGH to Output in Low-Z	t _{LZWE}	t _{en(W)}	0		0		ns
G LOW to Output in Low-Z	t _{LZOE}	t _{en(G)}	0		0		ns



Data Retention Mode

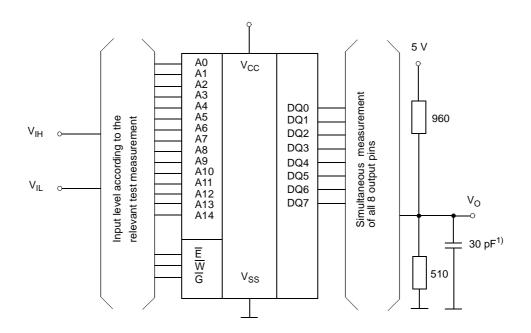
E-Controlled



 $V_{CC(DR)}$ - 0.2 $V \le V_{\overline{E}(DR)} \le V_{CC(DR)}$ + 0.3 V

Data Retention Characteristics	Symbol Alt. IEC		Conditions	Min.	Тур.	Max.	Unit
Data Retention Supply Voltage		V _{CC(DR)}		2		5.5	V
Data Retention Supply Current		I _{CC(DR)}	$V_{CC(DR)} = 3 V$ $V_{\overline{E}} = V_{CC(DR)-0.2V}$			30	μΑ
Data Retention Setup Time	t _{CDR}	t _{su(DR)}	See Data Retention	0			ns
Operating Recovery Time	t _R	t _{rec}	Waveforms (above)	t _{cR}			ns

Test Configuration for Functional Check



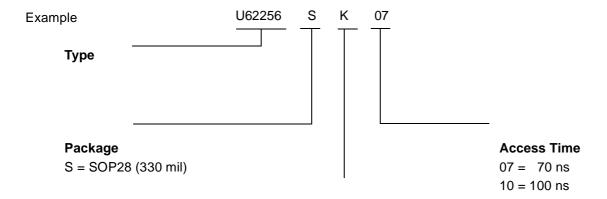
 $^{^{1)}} In \ measurement \ of \ t_{dis(E),} \ t_{dis(W)}, \ t_{dis(G)}, \ t_{en(E)}, \ t_{en(W)}, \ t_{en(G)} \ the \ capacitance \ is \ 5 \ pF.$



Capacitance	Conditions	Symbol	Min.	Max.	Unit
Input Capacitance	$V_{CC} = 5.0 \text{ V}$ $V_{I} = V_{SS}$	C _I	-	7	pF
Output Capacitance	$\begin{array}{ccc} f & = 1 \text{ MHz} \\ T_a & = 25 \text{ °C} \end{array}$	Co	-	7	pF

All pins not under test must be connected with ground by capacitors.

IC Code Numbers

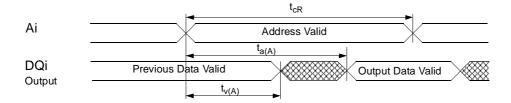


Operating Temperature Ranges

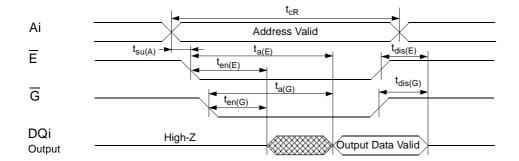
 $C = 0 \text{ to } 70 \text{ }^{\circ}\text{C}$ $K = -40 \text{ to } 85 \text{ }^{\circ}\text{C}$

The date of manufacture is given by the last 4 digits of the mark, the first 2 digits indicating the year, and the last 2 digits the calendar week.

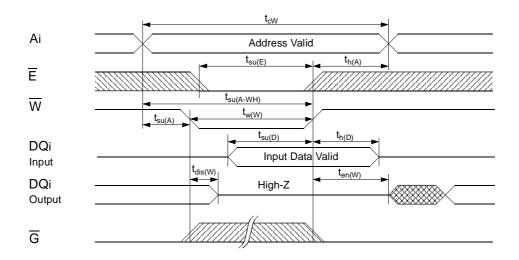
Read Cycle 1: Ai-controlled (during Read Cycle : $\overline{E} = \overline{G} = V_{IL}$, $\overline{W} = V_{IH}$)



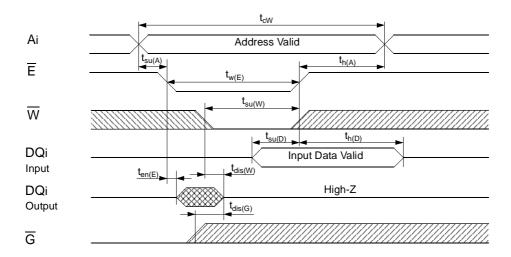
Read Cycle 2: \overline{G} -, \overline{E} -controlled (during Read Cycle: \overline{W} = V_{IH})



Write Cycle1: W-controlled



Write Cycle 2: E-controlled





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